

Description

The SI2310 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

D G S

SOT-23

General Features

 $V_{DS} = 60V I_D = 3A$

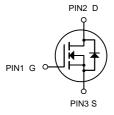
 $R_{DS(ON)}$ < $85m\Omega$ @ V_{GS} =10V

Application

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
SI2310	SOT-23	S10	3000PCS

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage	60	V
Vgs	Gate-Source Voltage	±20	V
Ι _D	Drain Current-Continuous	3	А
Ідм	Drain Current-Pulsed (Note 1)	10	А
Po	Maximum Power Dissipation	1.7	W
Тл,Твтв	Operating Junction and Storage Temperature Range		$^{\circ}$
Reja	Thermal Resistance,Junction-to-Ambient (Note 2)	73.5	°C/W



Electrical Characteristics (T_A=25°C unless otherwise noted)

Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	Characteristics (Note 3)					
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=250\mu A$	0.8	1.3	2.0	>
Drain-Source On-State Resistance	R _{DS(ON)}	V_{GS} =10V, I_D =3A	-	72	85	$m\Omega$
		V _{GS} =4.5V, I _D =1.5A	-	85	103	$m\Omega$
Forward Transconductance	g FS	V_{DS} =15 V , I_{D} =2 A		3	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	V _{DS} =30V,V _{GS} =0V, F=1.0MHz	-	510	ı	PF
Output Capacitance	C _{oss}		-	34	-	PF
Reverse Transfer Capacitance	C _{rss}	r-1.0ivii iz	-	26	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	6	-	nS
Turn-on Rise Time	t _r	V_{DD} =30 V , I_{D} =1.5 A	-	15	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10V, R_{GEN} =1 Ω	-	15	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Q_g	\/ -20\/ -24	-	7.5	-	nC
Gate-Source Charge	Q_{gs}	$V_{DS}=30V,I_{D}=3A,$ $V_{GS}=4.5V$	-	1.4	-	nC
Gate-Drain Charge	Q_{gd}	VGS-4.5V	-	3	-	nC
Drain-Source Diode Characteristics	ource Diode Characteristics					
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =3A	-	-	1.2	V
Diode Forward Current (Note 2)	I _S		-	-	3	Α

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

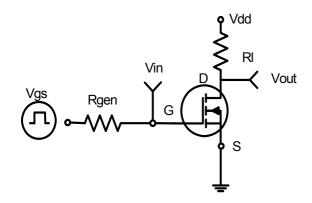


Figure 1:Switching Test Circuit

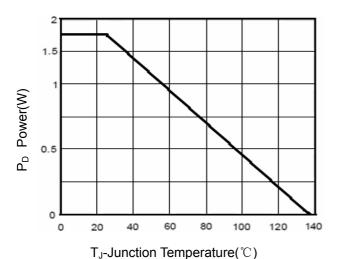


Figure 3 Power Dissipation

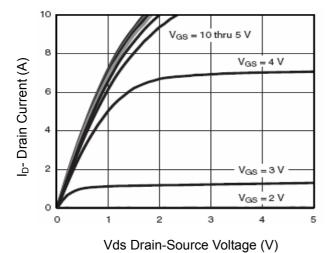


Figure 5 Output Characteristics

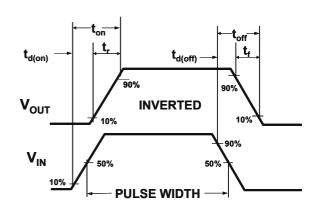


Figure 2:Switching Waveforms

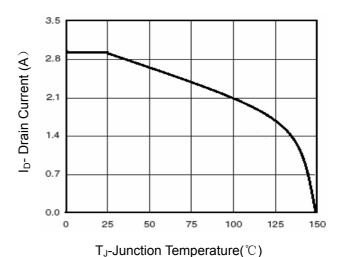


Figure 4 Drain Current

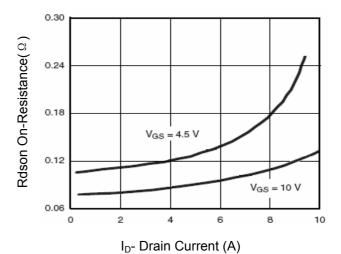


Figure 6 Drain-Source On-Resistance

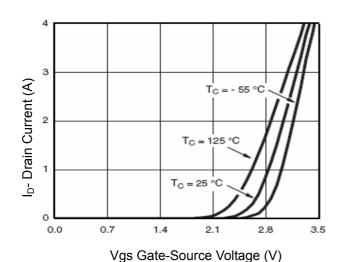
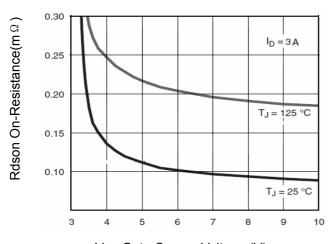


Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs

10

8

6

4

2

0

Vgs Gate-Source Voltage (V)

V_{DS}=30V I_D=3 A

Qg Gate Charge (nC)
Figure 11 Gate Charge

4

6

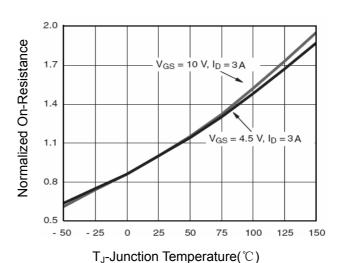
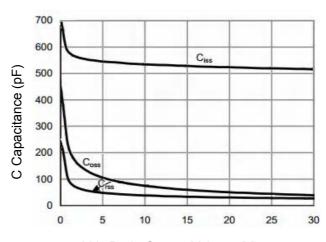


Figure 8 Drain-Source On-Resistance



Vds Drain-Source Voltage (V)

Figure 10 Capacitance vs Vds

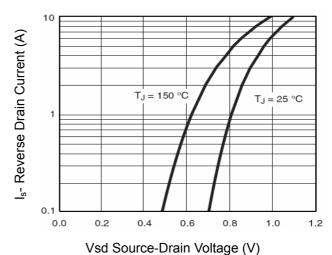


Figure 12 Source- Drain Diode Forward

2



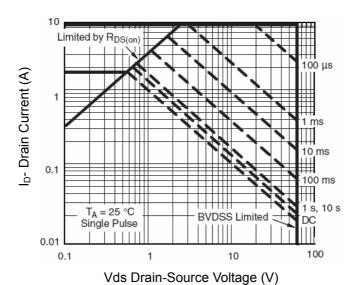


Figure 13 Safe Operation Area

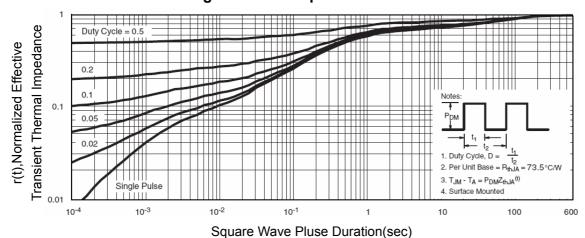
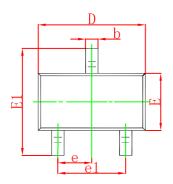
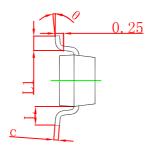


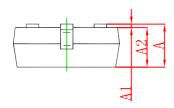
Figure 14 Normalized Maximum Transient Thermal Impedance



SOT-23 Package Outline Dimensions

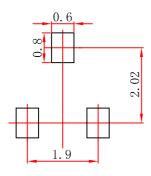






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Зупьоі	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



- Note:
 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.

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